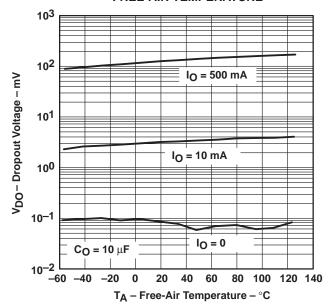
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- Open Drain Power-On Reset With 200-ms Delay (TPS775xx)
- Open Drain Power Good (TPS776xx)
- 500-mA Low-Dropout Voltage Regulator
- Available in 1.5-V, 1.8-V, 2.5-V, 2.8-V (TPS77628 Only), 3.3-V Fixed Output and Adjustable Versions
- Dropout Voltage to 169 mV (Typ) at 500 mA (TPS77x33)
- Ultra Low 85 μA Typical Quiescent Current
- Fast Transient Response
- 2% Tolerance Over Specified Conditions for Fixed-Output Versions
- 8-Pin SOIC and 20-Pin TSSOP PowerPAD™ (PWP) Package
- Thermal Shutdown Protection

description

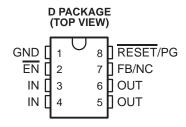
The TPS775xx and TPS776xx devices are designed to have a fast transient response and be stable with a 10- μ F low ESR capacitors. This combination provides high performance at a reasonable cost.

TPS77x33 DROPOUT VOLTAGE vs FREE-AIR TEMPERATURE

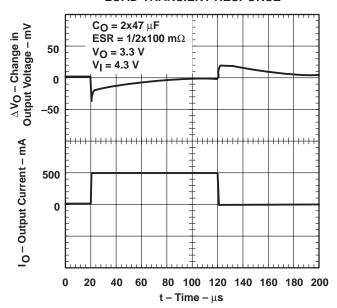


PWP PACKAGE (TOP VIEW) GND/HSINK [20 GND/HSINK 19 GND/HSINK GND/HSINK □ GND 18 **∏** NC NC 17 NC ΕN 16 RESET/PG 5 IN 15 T FB/NC 6 IN 14**∏** OUT 13 OUT NC [GND/HSINK [] 12 GND/HSINK GND/HSINK ∏ 11 I GND/HSINK

NC - No internal connection



TPS77x33 LOAD TRANSIENT RESPONSE





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments Incorporated

TEXAS INSTRUMENTS

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description (continued)

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 169 mV at an output current of 500 mA for the TPS77x33) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and independent of output loading (typically 85 μ A over the full range of output current, 0 mA to 500 mA). These two key specifications yield a significant improvement in operating life for battery-powered systems. This LDO family also features a sleep mode; applying a TTL high signal to $\overline{\text{EN}}$ (enable) shuts down the regulator, reducing the quiescent current to 1 μ A at $T_{\text{L}} = 25^{\circ}\text{C}$.

The RESET output of the TPS775xx initiates a reset in microcomputer and microprocessor systems in the event of an undervoltage condition. An internal comparator in the TPS775xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage.

Power good (PG) of the TPS776xx is an active high output, which can be used to implement a power-on reset or a low-battery indicator.

The TPS775xx and TPS776xx are offered in 1.5-V, 1.8-V, 2.5-V, 2.8 V (TPS77628 only), and 3.3-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.5 V to 5.5 V for TPS77501 option and 1.2 V to 5.5 V for TPS77601 option). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges. The TPS775xx and TPS776xx families are available in 8 pin SOIC and 20 pin TSSOP packages.

AVAILABLE OPTIONS†

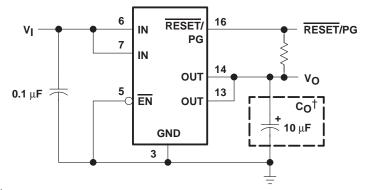
TJ	OUTPUT VOLTAGE (V)		PACKAGED	DEVICES	
	TYP	TSSOP (PWP)		SOIC (D)	
	3.3	TPS77533PWP	TPS77633PWP	TPS77533D	TPS77633D
	2.5	TPS77525PWP	TPS77625PWP	TPS77525D	TPS77625D
	2.8	_	TPS77628PWP		TPS77628D
	1.8	TPS77518PWP	TPS77618PWP	TPS77518D	TPS77618D
-40°C to 125°C	1.5	TPS77515PWP	TPS77615PWP	TPS77515D	TPS77615D
	Adjustable 1.2 V to 5.5 V	_	TPS77601PWP	_	TPS77601D
	Adjustable 1.5 V to 5.5 V	TPS77501PWP	_	TPS77501D	_

The TPS77x01 is programmable using an external resistor divider (see application information). The D and PWP packages are available taped and reeled. Add an R suffix to the device type (e.g., TPS77501DR).



[†] The TPS775xx has an open-drain power-on reset with a 200-ms delay function. The TPS776xx has an open-drain power good function.

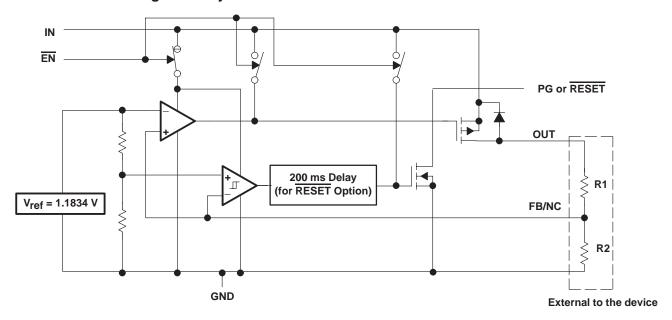
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[†] See application information section for capacitor selection details.

Figure 1. Typical Application Configuration for Fixed Output Options

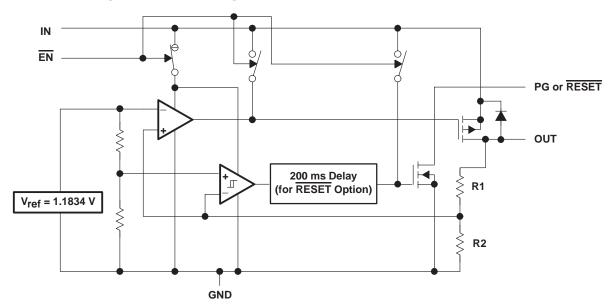
functional block diagram—adjustable version





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functional block diagram—fixed-voltage version





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Terminal Functions

SOIC Package (TPS775xx)

TERMIN	NAL	1/0	DESCRIPTION			
NAME	NO.	I/O	DESCRIPTION			
EN	2	I	Enable input			
FB/NC	7	I	Feedback input voltage for adjustable device (no connect for fixed options)			
GND	1		Regulator ground			
IN	3, 4	I	Input voltage			
OUT	5, 6	0	Regulated output voltage			
RESET	8	0	RESET output			

TSSOP Package (TPS775xx)

TER	TERMINAL		DESCRIPTION		
NAME	NO.	I/O	DESCRIPTION		
EN	5	Į	Enable input		
FB/NC	15	I	Feedback input voltage for adjustable device (no connect for fixed options)		
GND	3		Regulator ground		
GND/HSINK	1, 2, 9, 10, 11, 12, 19, 20		Ground/heatsink		
IN	6, 7	I	Input voltage		
NC	4, 8, 17, 18		No connect		
OUT	13, 14	0	Regulated output voltage		
RESET	16	0	RESET output		

SOIC Package (TPS776xx)

TERMIN	TERMINAL		DESCRIPTION			
NAME	NO.	1/0	DESCRIPTION			
EN	2	I	Enable input			
FB/NC	7	I	Feedback input voltage for adjustable device (no connect for fixed options)			
GND	1		Regulator ground			
IN	3, 4	I	Input voltage			
OUT	5, 6	0	Regulated output voltage			
PG	8	0	PG output			

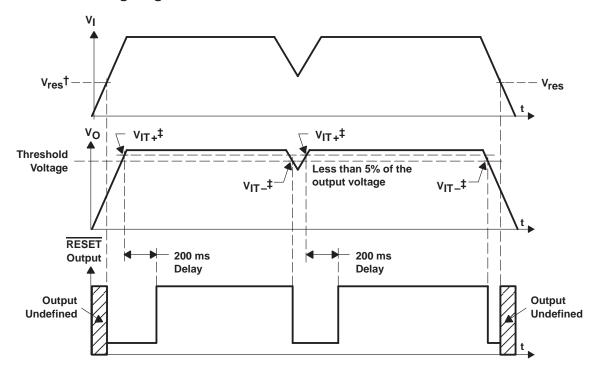
TSSOP Package (TPS776xx)

TER	TERMINAL		DESCRIPTION		
NAME	NO.	1/0	DESCRIPTION		
EN	5	I	Enable input		
FB/NC	15	I	Feedback input voltage for adjustable device (no connect for fixed options)		
GND	3		Regulator ground		
GND/HSINK	1, 2, 9, 10, 11, 12, 19, 20		Ground/heatsink		
IN	6, 7	I	Input voltage		
NC	4, 8, 17, 18		No connect		
OUT	13, 14	0	Regulated output voltage		
PG	16	0	PG output		



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TPS775xx RESET timing diagram



[†] V_{res} is the minimum input voltage for a valid RESET. The symbol V_{res} is not currently listed within EIA or JEDEC standards for semiconductor symbology.



 $[\]ddagger$ VIT –Trip voltage is typically 5% lower than the output voltage (95%VO) V_{IT} to V_{IT+} is the hysteresis voltage.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Input voltage range [‡] , V _I Voltage range at EN	
Maximum RESET voltage (TPS775xx)	
Maximum PG voltage (TPS776xx)	
Peak output current	Internally limited
Output voltage, V _O (OUT, FB)	
Continuous total power dissipation	See dissipation rating tables
Operating virtual junction temperature range, T _J	–40°C to 125°C
Storage temperature range, T _{stq}	–65°C to 150°C
ESD rating, HBM	2 kV

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE 1 – FREE-AIR TEMPERATURES

PACKAGE	AIR FLOW (CFM)	T _A < 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
D	0	568 mW	5.68 mW/°C	312 mW	227 mW
	250	904 mW	9.04 mW/°C	497 mW	361 mW

DISSIPATION RATING TABLE 2 - FREE-AIR TEMPERATURES

PACKAGE	AIR FLOW (CFM)	T _A < 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
PWP#	0	2.9 W	23.5 mW/°C	1.9 W	1.5 W
PWP"	300	4.3 W	34.6 mW/°C	2.8 W	2.2 W
DWDII	0	3 W	23.8 mW/°C	1.9 W	1.5 W
PWP∥	300	7.2 W	57.9 mW/°C	4.6 W	3.8 W

[#] This parameter is measured with the recommended copper heat sink pattern on a 1-layer PCB, 5-in × 5-in PCB, 1 oz. copper, 2-in × 2-in coverage (4 in²).

recommended operating conditions

		MIN	MAX	UNIT
Input voltage, V _I ☆		2.7	10	V
Output voltage range V-	TPS77501	1.5	5.5	V
Output voltage range, VO	TPS77601	1.2	5.5	V
Output current, IO (Note 1)	•	0	500	mA
Operating virtual junction temperature, T _J (Note 1)	-40	125	°C	

★ To calculate the minimum input voltage for your maximum output current, use the following equation: V_{I(min)} = V_{O(max)} + V_{DO(max load)}.
NOTE 1: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.



[‡] All voltage values are with respect to network terminal ground.

This parameter is measured with the recommended copper heat sink pattern on a 8-layer PCB, 1.5-in × 2-in PCB, 1 oz. copper with layers 1, 2, 4, 5, 7, and 8 at 5% coverage (0.9 in²) and layers 3 and 6 at 100% coverage (6 in²). For more information, refer to TI technical brief SLMA002.

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electrical characteristics <u>ov</u>er recommended operating free-air temperature range, $V_i = V_{O(typ)} + 1$ V, $I_O = 1$ mA, $\overline{EN} = 0$ V, $C_O = 10$ μF (unless otherwise noted)

	PARAMETER		TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
		TPS77501	$1.5 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$	T _J = 25°C		٧o		
		117577501	$1.5 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$	$T_J = -40^{\circ}C$ to $125^{\circ}C$	0.98V _O		1.02V _O	
		TPS77601	$1.2 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$	T _J = 25°C		٧o		
		11-377001	$1.2 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	0.98V _O		1.02V _O	
		TPS77x15	$T_J = 25^{\circ}C$,	$2.7 \text{ V} < \text{V}_{1N} < 10 \text{ V}$		1.5		
		11-3/7/13	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C},$	$2.7 \text{ V} < \text{V}_{1N} < 10 \text{ V}$	1.470		1.530	
Output voltag	,	TPS77x18	T _J = 25°C,	$2.8 \text{ V} < \text{V}_{1N} < 10 \text{ V}$		1.8		V
(see Note 2)	TilA load)	11 377×10	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C},$	$2.8 \text{ V} < \text{V}_{1N} < 10 \text{ V}$	1.764		1.836	V
		TPS77x25	T _J = 25°C,	$3.5 \text{ V} < \text{V}_{1N} < 10 \text{ V}$		2.5		
		11 377 723	$T_J = -40^{\circ}\text{C to } 125^{\circ}\text{C},$	$3.5 \text{ V} < \text{V}_{\text{IN}} < 10 \text{ V}$	2.450		2.550	
		TPS77628		3.8 V < V _{IN} < 10 V		2.8		
		11 077020	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C},$	3.8 V < V _{IN} < 10 V	2.744		2.856	
		TPS77x33	T _J = 25°C,	4.3 V < V _{IN} < 10 V		3.3		
		11 077,000	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$	4.3 V < V _{IN} < 10 V	3.234		3.366	
	rrent (GND current)		$10 \mu A < I_O < 500 mA$,	T _J = 25°C		85		μΑ
$\overline{EN} = 0V$, (see	e Note 2)		$I_O = 500 \text{ mA},$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			125	μΛ
Output voltage line regulation (ΔV _O /V _O) (see Notes 2 and 3)		$V_{O} + 1 V < V_{I} \le 10 V$	T _J = 25°C		0.01		%/V	
Load regulation	on					3		mV
Output noise voltage		BW = 300 Hz to 50 kH $C_0 = 10 \mu F$,	z, T _J = 25°C		190		μVrms	
Output currer	Output current Limit		V _O = 0 V			1.7	2	Α
Thermal shut	down junction temperatu	re				150		°C
0. "			EN = V _I ,	T _J = 25°C, 2.7 V < V _I < 10 V		1		μΑ
Standby curre	ent		EN = V _I ,	$T_J = -40^{\circ}\text{C to } 125^{\circ}\text{C}$ 2.7 V < V _I < 10 V			10	μΑ
FB input curre	ent	TPS77x01	FB = 1.5 V			2		nA
High level ena	able input voltage				1.7			V
Low level ena	able input voltage						0.9	V
Power supply	ripple rejection (see Not	e 2)	f = 1 KHz, T _J = 25°C	$C_{O} = 10 \mu F$,		60		dB
	Minimum input voltage t	for valid RESET	I _{O(RESET)} = 300μA			1.1		V
Trip threshold voltage		V _O decreasing		92		98	%Vo	
Reset Hysteresis voltage		Measured at VO			0.5		%Vo	
(TPS775xx) Output low voltage		V _I = 2.7 V,	IO(RESET) = 1mA		0.15	0.4	V	
	Leakage current		V _(RESET) = 5 V	- /			1	μΑ
	RESET time-out delay		()			200		ms
Minimum input voltage for valid PG		I _O (PG) = 300μA			1.1		V	
	Trip threshold voltage	-	V _O decreasing		92		98	%Vo
PG (TDC776)(V)	Hysteresis voltage		Measured at VO			0.5		%Vo
(TPS776xx)	Output low voltage		V _I = 2.7 V,	I _O (PG) = 1mA		0.15	0.4	V
	Leakage current		V _(PG) = 5 V	<u> </u>			1	μΑ
			(.)					

NOTE 2: Minimum IN operating voltage is 2.7 V or V_{O(tvp)} + 1 V, whichever is greater. Maximum IN voltage 10V.



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electrical characteristics over recommended operating free-air temperature range, $V_i = V_{O(typ)} + 1$ V, $I_O = 1$ mA, $\overline{EN} = 0$ V, $C_O = 10~\mu F$ (unless otherwise noted) (continued)

PARAMETER		TEST	TEST CONDITIONS		TYP	MAX	UNIT
Input current (EN)		<u>EN</u> = 0 V		-1	0	1	^
		EN = V _I		-1		1	μΑ
	TPS77628	$I_O = 500 \text{ mA},$	T _J = 25°C		285		
	17377020	$I_O = 500 \text{ mA},$	$T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			410	
Dropout voltage	TPS77533	$I_O = 500 \text{ mA},$	T _J = 25°C		169		mV
(See Note 4)		I _O = 500 mA,	$T_J = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			287	IIIV
	TD077000	I _O = 500 mA,	T _J = 25°C		169		
	TPS77633	$I_{O} = 500 \text{ mA},$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			287	

NOTES: 3. If $V_0 \le 1.8 \text{ V}$ then $V_{imin} = 2.7 \text{ V}$, $V_{imax} = 10 \text{ V}$:

Line Reg. (mV) =
$$(\%/V) \times \frac{V_O(V_{imax} - 2.7 \text{ V})}{100} \times 1000$$

If $V_0 \ge 2.5 \text{ V}$ then $V_{imin} = V_0 + 1 \text{ V}$, $V_{imax} = 10 \text{ V}$:

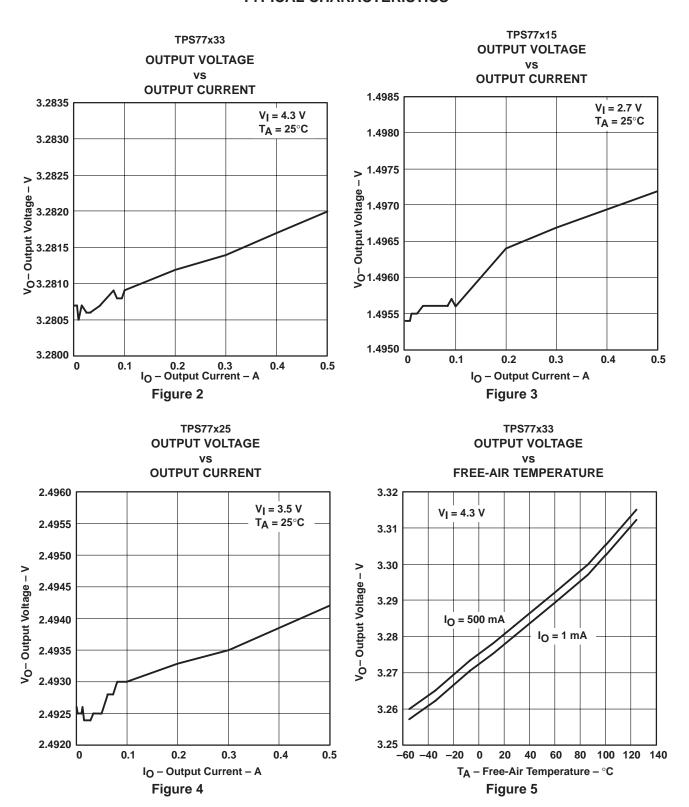
Line Reg. (mV) =
$$(\%/V) \times \frac{V_O(V_{imax} - (V_O + 1 \ V))}{100} \times 1000$$

4. IN voltage equals V_O(Typ) – 100 mV; TPS77x15, TPS77x18, and TPS77x25 dropout voltage limited by input voltage range limitations (i.e., TPS77x33 input voltage needs to drop to 3.2 V for purpose of this test).

Table of Graphs

			FIGURE
۷o	Output valtage	vs Output current	2, 3, 4
	Output voltage	vs Free-air temperature	5, 6, 7
	Ground current	vs Free-air temperature	8
	Power supply ripple rejection	vs Frequency	9
	Output spectral noise density	vs Frequency	10
Zo	Output impedance	vs Frequency	11
\/	Dropout voltage	vs Input voltage	12
VDO	Dropout voltage	vs Free-air temperature	13
	Line transient response		14, 16
	Load transient response		15, 17
	Output voltage	vs Time	18
	Equivalent series resistance (ESR)	vs Output current	20 – 23

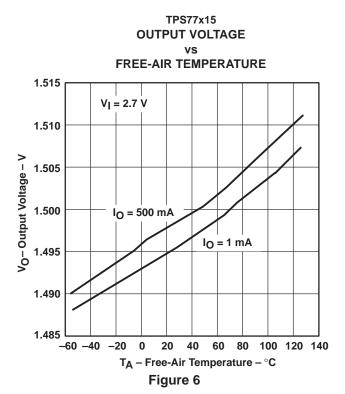
TYPICAL CHARACTERISTICS

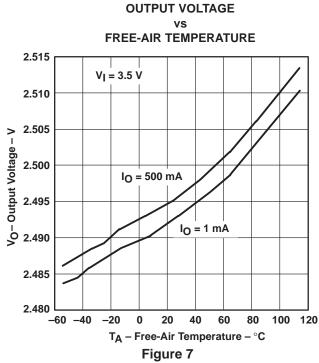


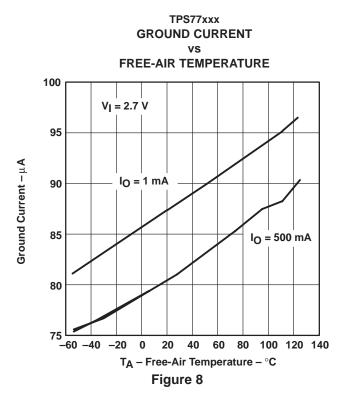


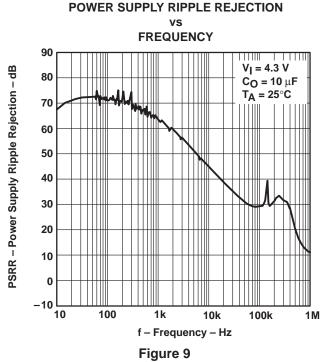
TPS77x25

TYPICAL CHARACTERISTICS



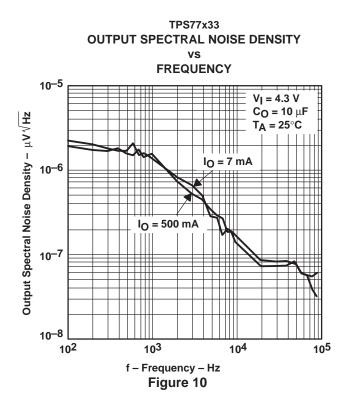


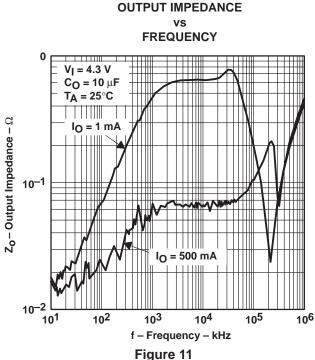




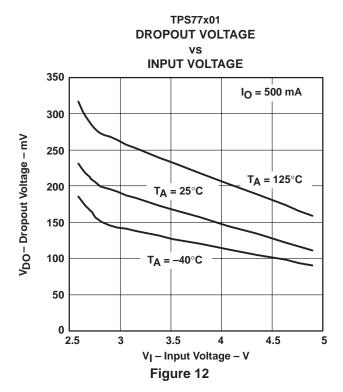
TPS77x33

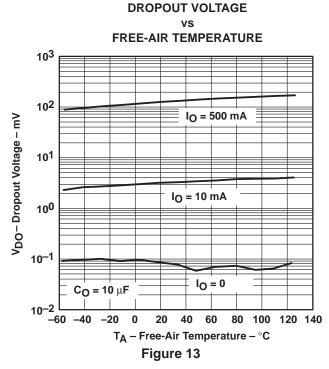
TYPICAL CHARACTERISTICS





TPS77x33





TPS77x33

Figure 17

TYPICAL CHARACTERISTICS

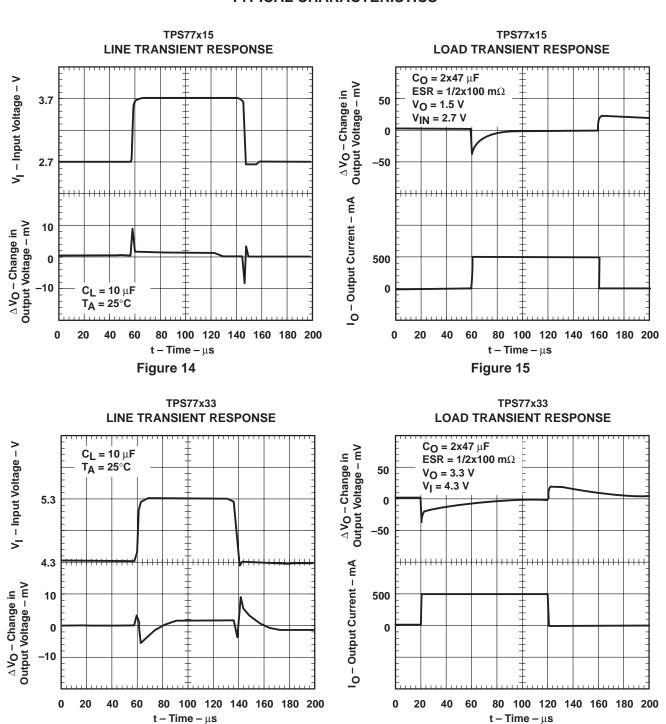


Figure 16

TYPICAL CHARACTERISTICS

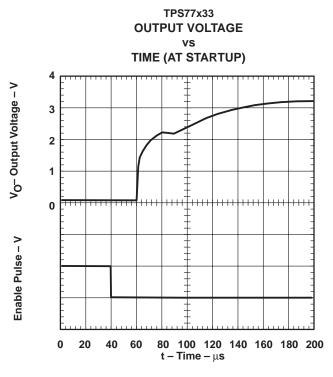


Figure 18

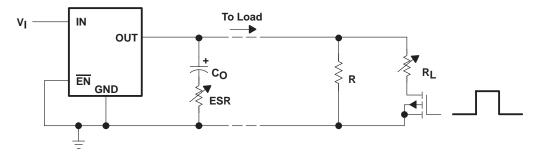


Figure 19. Test Circuit for Typical Regions of Stability (Figures 20 through 23) (Fixed Output Options)

TYPICAL CHARACTERISTICS

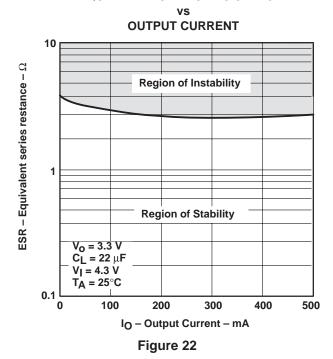
EQUIVALENT SERIES RESISTANCE[†] vs **OUTPUT CURRENT** 10 **=SR** − Equivalent series restance − Ω Region of Instability Region of Stability $V_0 = 3.3 \text{ V}$ $C_L = 4.7 \mu F$ $V_{1} = 4.3 \text{ V}$ T_A = 25°C 100 0 200 300 400 500

TYPICAL REGION OF STABILITY

Figure 20

IO - Output Current - mA

TYPICAL REGION OF STABILITY EQUIVALENT SERIES RESISTANCE[†]



TYPICAL REGION OF STABILITY EQUIVALENT SERIES RESISTANCE[†]



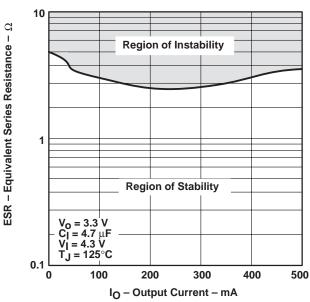
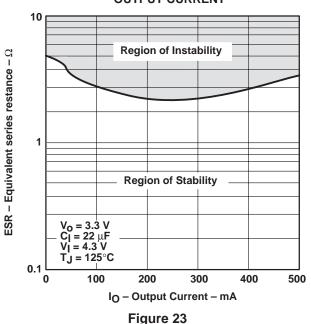


Figure 21

TYPICAL REGION OF STABILITY EQUIVALENT SERIES RESISTANCE[†]

OUTPUT CURRENT



[†] Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to Co.



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APPLICATION INFORMATION

The TPS775xx family includes four fixed-output voltage regulators (1.5 V, 1.8 V, 2.5 V, and 3.3 V), and an adjustable regulator, the TPS77501 (adjustable from 1.5 V to 5.5 V).

The TPS776xx family includes five fixed-output voltage regulators (1.5 V, 1.8 V, 2.5 V, 2.8 V, and 3.3 V), and an adjustable regulator, the TPS77601 (adjustable from 1.2 V to 5.5 V).

device operation

The TPS775xx and TPS776xx feature very low quiescent current, which remains virtually constant even with varying loads. Conventional LDO regulators use a pnp pass element, the base current of which is directly proportional to the load current through the regulator ($I_B = I_C/\beta$). The TPS775xx and TPS776xx use a PMOS transistor to pass current; because the gate of the PMOS is voltage driven, operating current is low and invariable over the full load range.

Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in β forces an increase in I_B to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS775xx and TPS776xx quiescent currents remain low even when the regulator drops out, eliminating both problems.

The TPS775xx and TPS776xx families also feature a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces quiescent current to $2\,\mu\text{A}$. If the shutdown feature is not used, $\overline{\text{EN}}$ should be tied to ground. Response to an enable transition is quick; regulated output voltage is typically reestablished in 120 μS .

minimum load requirements

The TPS775xx and TPS776xx families are stable even at zero load; no minimum load is required for operation.

FB - pin connection (adjustable version only)

The FB pin is an input pin to sense the output voltage and close the loop for the adjustable option . The output voltage is sensed through a resistor divider network to close the loop as it is shown in Figure 25. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit to improve performance at that point. Internally, FB connects to a high-impedance wide-bandwidth amplifier and noise pickup feeds through to the regulator output. Routing the FB connection to minimize/avoid noise pickup is essential.

external capacitor requirements

An input capacitor is not usually required; however, a ceramic bypass capacitor (0.047 μ F or larger) improves load transient response and noise rejection if the TPS775xx or TPS776xx are located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

Like all low dropout regulators, the TPS775xx and TPS776xx require an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 10 μ F and the ESR (equivalent series resistance) must be between 50 m Ω and 1.5 Ω . Capacitor values 10 μ F or larger are acceptable, provided the ESR is less than 1.5 Ω . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described previously.



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APPLICATION INFORMATION

external capacitor requirements (continued)

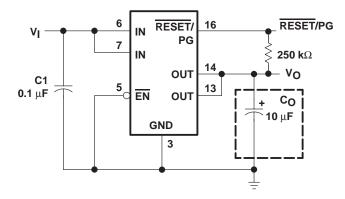


Figure 24. Typical Application Circuit (Fixed Versions)

programming the TPS77x01 adjustable LDO regulator

The output voltage of the TPS77x01 adjustable regulator is programmed using an external resistor divider as shown in Figure 25. The output voltage is calculated using:

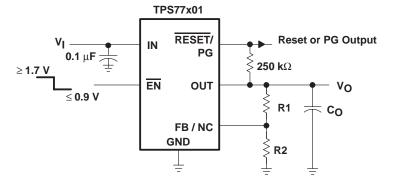
$$V_{O} = V_{ref} \times \left(1 + \frac{R1}{R2}\right) \tag{1}$$

Where

V_{ref} = 1.1834 V typ (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 10- μ A divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 110 k Ω to set the divider current at approximately 10 μ A and then calculate R1 using:

$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \times R2 \tag{2}$$



OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	UNIT
2.5 V	121	110	kΩ
3.3 V	196	110	kΩ
3.6 V	226	110	kΩ
4.75 V	332	110	kΩ

Figure 25. TPS77x01 Adjustable LDO Regulator Programming

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APPLICATION INFORMATION

reset indicator

The TPS775xx features a RESET output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the RESET output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. RESET can be used to drive power-on reset circuitry or as a low-battery indicator. RESET does not assert itself when the regulated output voltage falls outside the specified 2% tolerance, but instead reports an output voltage low relative to its nominal regulated value (refer to timing diagram for start-up sequence).

power-good indicator

The TPS776xx features a power-good (PG) output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the PG output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. PG can be used to drive power-on reset circuitry or used as a low-battery indicator.

regulator protection

The TPS775xx and TPS776xx PMOS-pass transistors have a built-in back diode that conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS775xx and TPS776xx also feature internal current limiting and thermal protection. During normal operation, the TPS775xx and TPS776xx limit output current to approximately 1.7 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.



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APPLICATION INFORMATION

power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(max)}$, and the actual dissipation, P_{D} , which must be less than or equal to $P_{D(max)}$.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{J}max - T_{A}}{R_{\theta JA}}$$

Where

T_Jmax is the maximum allowable junction temperature

 $R_{\theta JA}$ is the thermal resistance junction-to-ambient for the package, i.e., 176°C/W for the 8-terminal SOIC and 32.6°C/W for the 20-terminal PWP with no airflow.

T_A is the ambient temperature.

The regulator dissipation is calculated using:

$$P_{D} = (V_{I} - V_{O}) \times I_{O}$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.



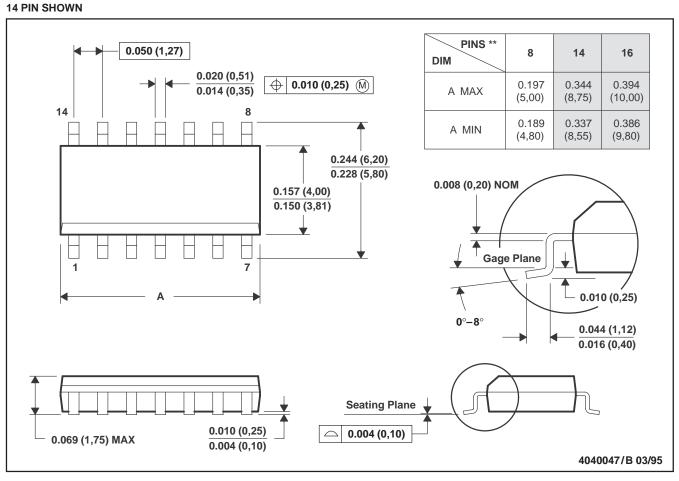
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MECHANICAL DATA

D (R-PDSO-G**)

(...

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
- D. Four center pins are connected to die mount pad.
- E. Falls within JEDEC MS-012

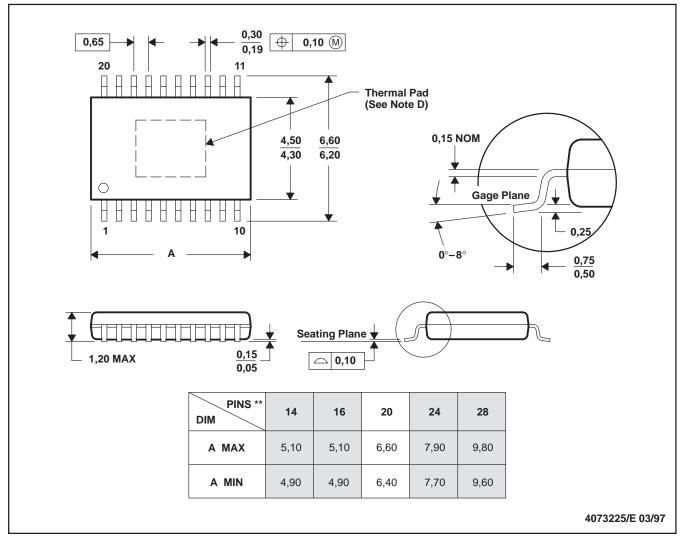
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MECHANICAL DATA

PWP (R-PDSO-G**)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE

20-PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusions.
 - D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
 - E. Falls within JEDEC MO-153

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